

MOSFET – Power, Single N-Channel, Logic Level, SO8FL

40 V, 0.7 mΩ, 349 A

NTMFS0D7N04XL

Features

- Low R_{DS(on)} to Minimize Conduction Loss
- Low Q_{RR} with Soft Recovery to Minimize E_{RR} Loss and Voltage Spike
- Low Q_G and Capacitance to Minimize Driving and Switching Loss
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- High Switching Frequency DC-DC Conversion
- Synchronous Rectification

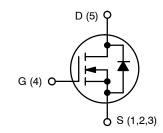
MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

Parameter	Symbol	Value	Unit	
Drain-to-Source Voltage		V_{DSS}	40	V
Gate-to-Source Voltage	DC	V _{GS}	±20	V
Continuous Drain Current	T _C = 25°C	I _D	349	Α
(Note 2)	T _C = 100°C		247	
Power Dissipation (Note 2)	T _C = 25°C	P _D	167	W
	T _C = 100°C		83	
Pulsed Drain Current	T _C = 25°C,	I _{DM}	1667	Α
Pulsed Source Current (Body Diode)	t _p = 100 μs	I _{SM}	1667	
Operating Junction and Storage Range	T _J , T _{STG}	-55 to +175	°C	
Source Current (Body Diode)	IS	256	Α	
Single Pulse Avalanche Energy (Note 3)	E _{AS}	470	mJ	
Lead Temperature for Soldering (1/8" from case for 10 s)	T _L	260	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Surface-mounted on FR4 board using 1 in² pad size, 1 oz Cu pad.
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 3. E_{AS} of 470 mJ is based on started T_J = 25°C, I_{AS} = 97 A, V_{DD} = 32 V, V_{GS} = 10 V, 100% avalanche tested.
- 4. $R_{\theta JCT}$ Thermal Resistance Junction to Case Top = 20 °C/W.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
40 V	0.7 mΩ @ 10 V	349 A
40 V	1.1 mΩ @ 4.5 V	349 A



N-CHANNEL MOSFET

MARKING DIAGRAM





0D7N4L = Specific Device Code A = Assembly Location Y = Year

W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering, marking and shipping information on page 6 of this data sheet.

THERMAL CHARACTERISTICS

Parameter		Value	Unit
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	0.9	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	38	

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•					•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 1 \text{ mA}$	40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	$\Delta V_{(BR)DSS}/ \Delta T_J$	I _D = 1 mA, Referenced to 25°C		16.6		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, T _J = 25°C			10	μΑ
		V _{DS} = 40 V, T _J = 125°C			100	1
Gate-to-Source Leakage Current	I _{GSS}	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
ON CHARACTERISTICS						
Drain-to-Source On Resistance	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 49 \text{ A}$		0.58	0.7	mΩ
		V _{GS} = 6 V, I _D = 49 A		0.66	0.9	1
		V _{GS} = 4.5 V, I _D = 39 A		0.77	1.1	1
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D = 250 \mu A$	1.3		2.2	V
Gate Threshold Voltage Temperature Coefficient	ΔV _{GS(TH)} / ΔΤ _J	$V_{GS} = V_{DS}$, $I_D = 250 \mu A$		-5.35		mV/°C
Forward Transconductance	9FS	V _{DS} = 5 V, I _D = 49 A		245		S
CHARGES, CAPACITANCES & GATE RES	SISTANCE					
Input Capacitance	C _{ISS}			7090		pF
Output Capacitance	C _{OSS}	V _{GS} = 0 V, V _{DS} = 20 V, f = 1 MHz		1860		
Reverse Transfer Capacitance	C _{RSS}			40		1
Output Charge	Q _{OSS}	V _{GS} = 0 V, V _{DS} = 20 V		72		nC
Total Gate Charge	Q _{G(TOT)}	$V_{GS} = 4.5 \text{ V}, V_{DD} = 20 \text{ V}; I_D = 49 \text{ A}$		42		
		V _{GS} = 6 V, V _{DD} = 20 V; I _D = 49 A		57		
		V _{GS} = 10 V, V _{DD} = 20 V; I _D = 49 A		96		
Threshold Gate Charge	Q _{G(TH)}			11		
Gate-to-Source Charge	Q _{GS}	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\		20		
Gate-to-Drain Charge	Q _{GD}	$V_{GS} = 10 \text{ V}, V_{DD} = 20 \text{ V}; I_D = 49 \text{ A}$		6		
Gate Plateau Voltage	V _{GP}			2.89		V
Gate Resistance	R _G	f = 1 MHz		0.5		Ω
SWITCHING CHARACTERISTICS						
Turn-On Delay Time	t _{d(ON)}			25		ns
Rise Time	t _r	Resistive Load,		7		1
Turn-Off Delay Time	t _{d(OFF)}	$V_{GS} = 0/10 \text{ V}, V_{DD} = 20 \text{ V},$ $I_{D} = 49 \text{ A}, R_{G} = 2.5 \Omega$		64		1
Fall Time	t _f			5		1

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
SOURCE-TO-DRAIN DIODE CHARACTERISTICS						
Forward Diode Voltage	V_{SD}	$V_{GS} = 0 \text{ V}, I_S = 49 \text{ A}, T_J = 25^{\circ}\text{C}$		0.8	1.2	V
		V _{GS} = 0 V, I _S = 49 A, T _J = 125°C		0.65		
Reverse Recovery Time	t _{RR}			39		ns
Charge Time	t _a	V _{GS} = 0 V, dI/dt = 300 A/μs,		21		
Discharge Time	t _b	$V_{GS} = 0 \text{ V, dI/dt} = 300 \text{ A/}\mu\text{s,}$ $I_{S} = 49 \text{ A, V}_{DD} = 20 \text{ V}$		18		
Reverse Recovery Charge	Q _{RR}			87		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

1200

V_{DS}=5V

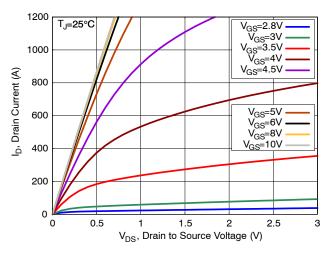
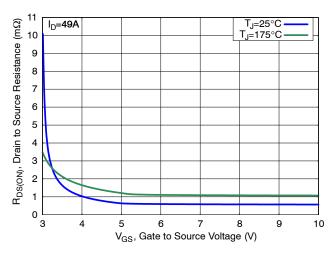


Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



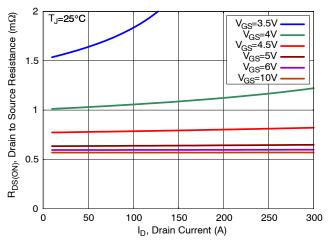
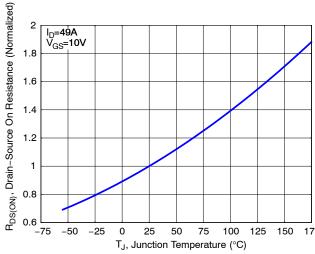


Figure 3. On-Resistance vs. Gate Voltage

Figure 4. On-Resistance vs. Drain Current





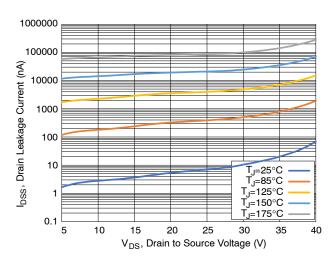


Figure 6. Drain Leakage Current vs. Drain Voltage

TYPICAL CHARACTERISTICS (CONTINUED)

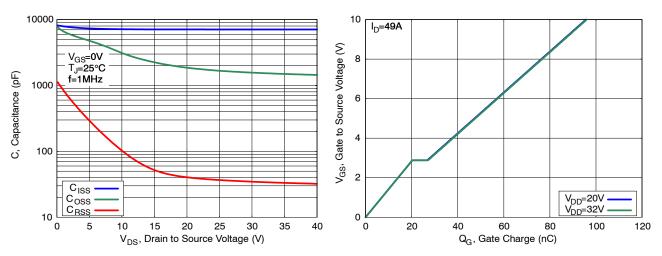


Figure 7. Capacitance Characteristics

Figure 8. Gate Charge Characteristics

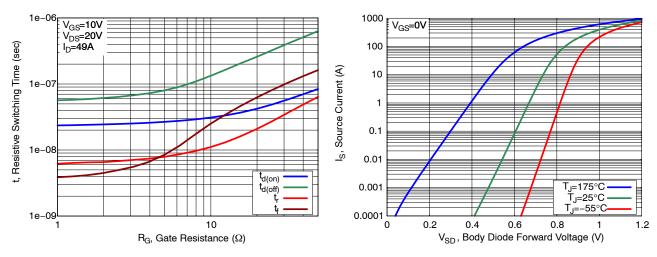


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

Figure 10. Diode Forward Characteristics

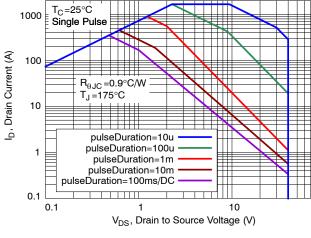


Figure 11. Safe Operating Area (SOA)

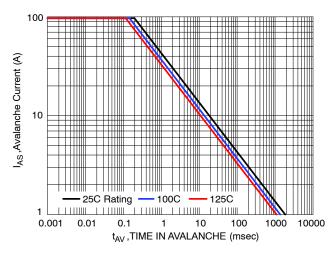


Figure 12. Avalanche Current vs. Pulse Time (UIS)

TYPICAL CHARACTERISTICS (CONTINUED)

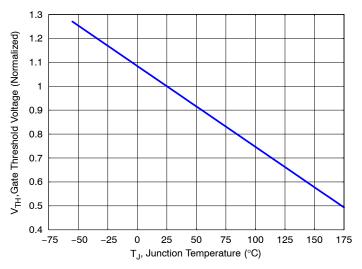


Figure 13. Gate Threshold Voltage vs. Junction Temperature

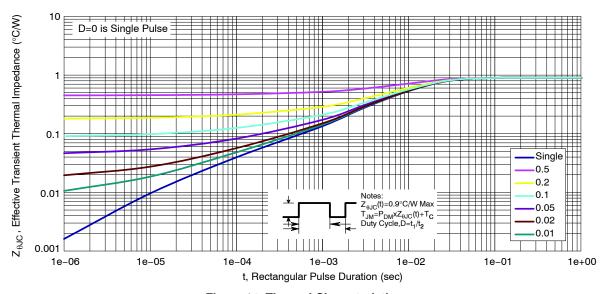


Figure 14. Thermal Characteristics

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NTMFS0D7N04XLT1G	0D7N4L	DFN5 (Pb-Free)	1500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SIDE VIEW





DFN5 5x6, 1.27P (SO-8FL) CASE 488AA ISSUE N

DATE 25 JUN 2018

NOTES:

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETER. DIMENSION D1 AND E1 DO NOT INCLUDE
- MOLD FLASH PROTRUSIONS OR GATE BURRS

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.90	1.00	1.10	
A1	0.00		0.05	
b	0.33	0.41	0.51	
С	0.23	0.28	0.33	
D	5.00	5.15	5.30	
D1	4.70	4.90	5.10	
D2	3.80	4.00	4.20	
E	6.00	6.15	6.30	
E1	5.70	5.90	6.10	
E2	3.45	3.65	3.85	
е		1.27 BSC	;	
G	0.51	0.575	0.71	
K	1.20	1.35	1.50	
L	0.51	0.575	0.71	
L1	0.125 REF			
М	3.00	3.40	3.80	
θ	0 °		12 °	

GENERIC MARKING DIAGRAM*

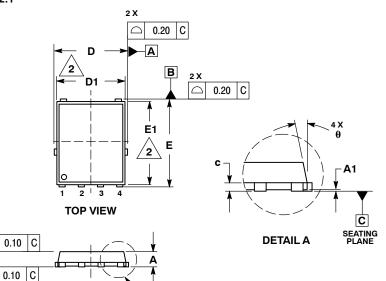


XXXXXX = Specific Device Code

= Assembly Location Α

Υ = Year W = Work Week = Lot Traceability ZZ

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.





DETAIL A

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	DFN5 5x6, 1.27P (SO-8FL)		PAGE 1 OF 1

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